

### **Technical Data Sheet**

#### MODEL NO: Q110ANR4

3010 Package 3.0\*1.0\*2.0mm Chip LEDs

Features:

•Package in 8mm tape on 7" diameter reel

•Compatible with automatic placement equipment

•Compatible with reflow solder process

Applications:

Indicators

•Automotive : backlighting in dashboard and switch

Backlight for LCD

Dice material	Emitted color	Lens Color
AlGaInP	RED	
		Water transparent

### Electrical/Optical Characteristics(Ta=25°C)

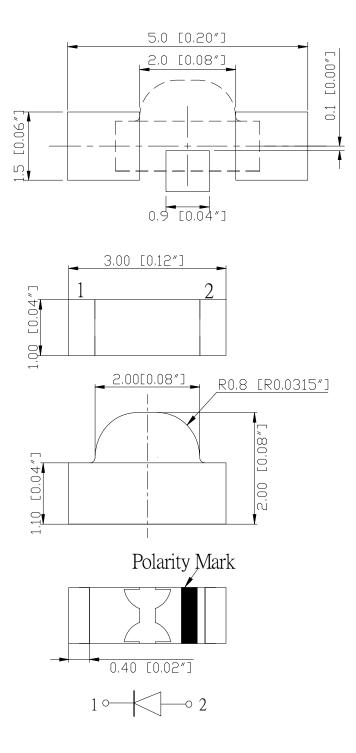
Parameter	Test	Symbol	Value		l lmit	
	Condition		Min	Тур	Max	Unit
Wavelength at peak emission	lf=20mA	$\lambda$ peak		658		nm
Spectral half bandwidth	lf=20mA	$\bigtriangleup \lambda$		17		nm
Dominant wavelength	lf=20mA	$\lambda$ dom	630	642	650	nm
Forward voltage	lf=20mA	Vf	1.7	2.0	2.5	V
Luminous intensity	lf=20mA	lv	63	115	200	mcd
Viewing angle at 50% lv	lf=100mA	2 <i>                                    </i>		150		Deg
Reverse current	Vr=500V	lr			10	μA

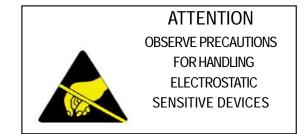
### Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Value	Unit
Power dissipation	Pd	75	mW
Forward current	lf	30	mA
Reverse voltage	Vr	5	V
Operating temperature range	Тор	-40 ~+80	°C
Storage temperature range	Tstg	-40 ~+80	°C
Peak pulsing current (1/8 duty f=1kHz)	lfp	125	mA



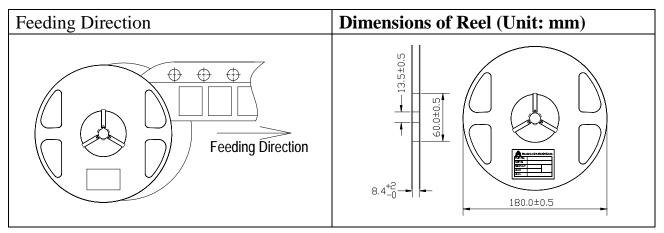
## PACKAGING DIMENSIONS (mm):

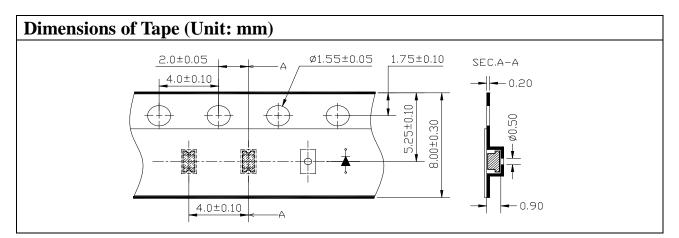


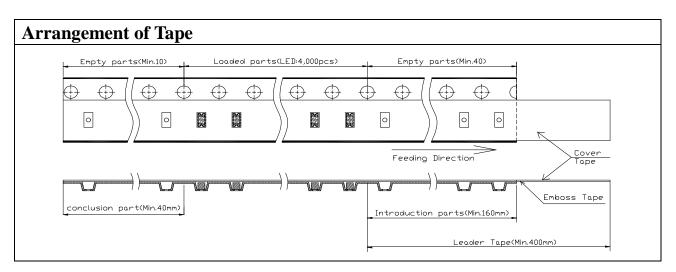




## PACKAGING SPECIFICATIONS





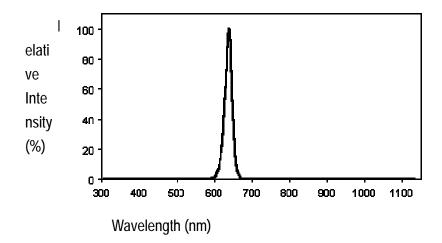


#### NOTES

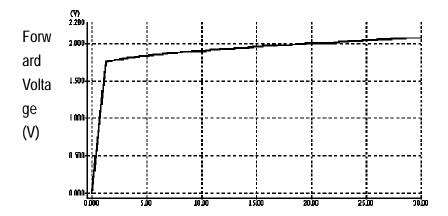
- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamps is two;
- 3. The polarity mark is oriented towards the tape sprocket hole ;
- 4. 3,000pcs/Reel.



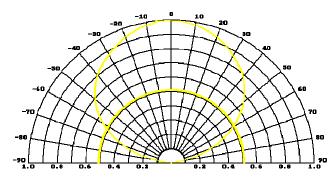
Relative Intensity vs. Wavelength



Forward Current vs. Forward Voltage



Forward Current vs. Forward Voltage



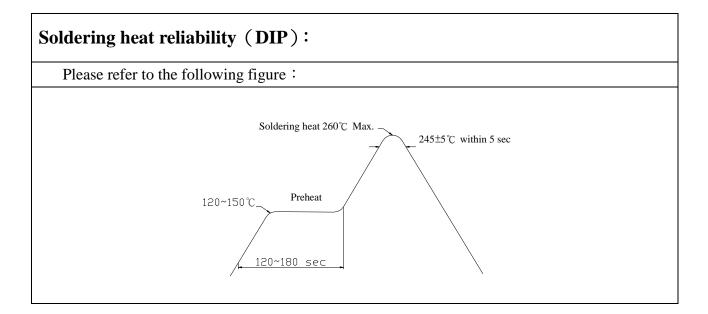
**Directive Characteristics** 



### **Descriptions** :

The Chip-LED Taping is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.

Besides, lightweight makes them ideal for miniature application, etc.



#### **Precautions For Use :**

#### **Over - current - proof**

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

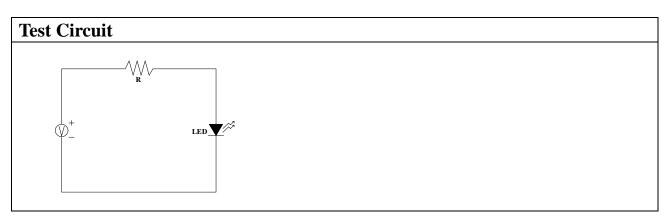
#### Storage

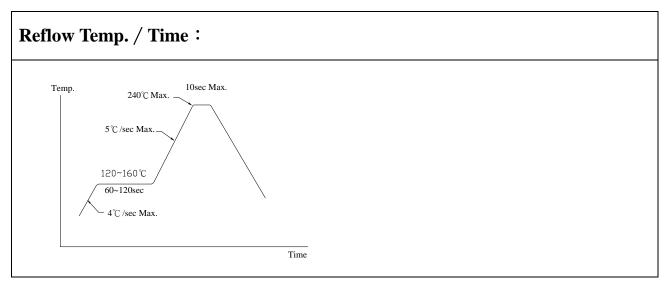
1. The operation of temperature and R.H. are  $: 5^{\circ}$ C  $\sim 30^{\circ}$ C,  $60^{\circ}$ R.H. Max.

2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).

3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is :  $60^{\circ}C\pm 5^{\circ}C$  for 15 hrs.







Reliability Test Items And Conditions							
The reliability of products shal be satisfied with items listed below.							
No.	Items	Test Condition	Test Hours/Cycles	Sample Size			
1	Solder Heat	$TEMP: 260^{\circ}C \pm 5^{\circ}C \qquad 5 \text{ sec}$		48 pcs			
2	Temperature Cycle	90°C ~ 25°C ~ -30°C ~ 25 °C 30m 5m 30m 5m	300Cycles	48 Pcs			
3	Thermal Shick	100°C ~ -55°C 10m 10m	100Cycles	48 Pcs			
4	Operation Life	If=20mA	1000 Hrs	48 Pcs			
5	High Temperature Storage	Temp:90°C	1000Hrs	48 Pcs			
6	Low Temperature Storage	Temp:-30°C	1000Hrs	48 Pcs			
7	High Temperature/High Humidity	80°C / R.H80%	1000Hrs	48 Pcs			